

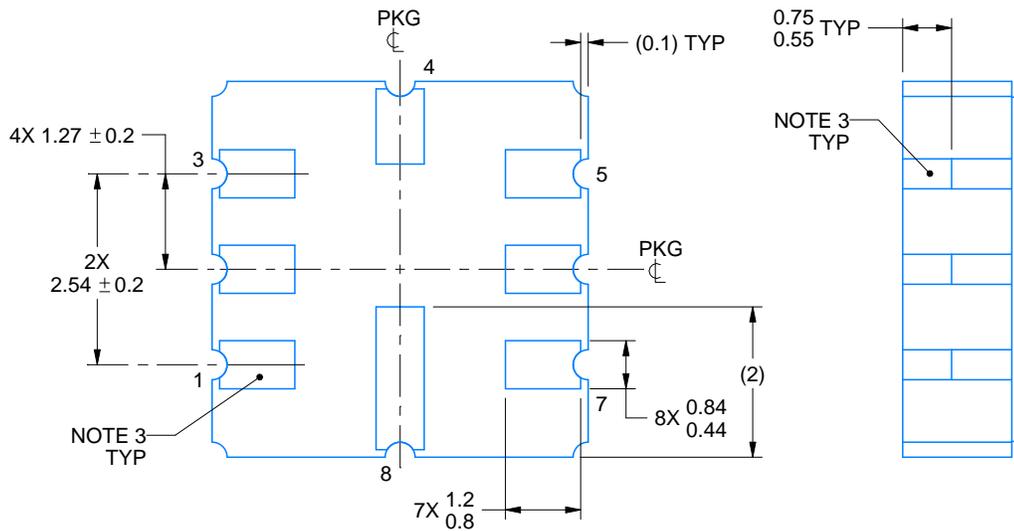
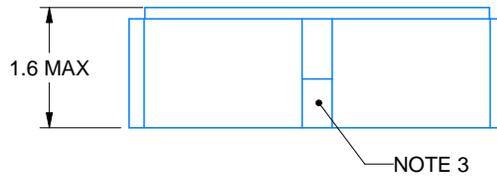
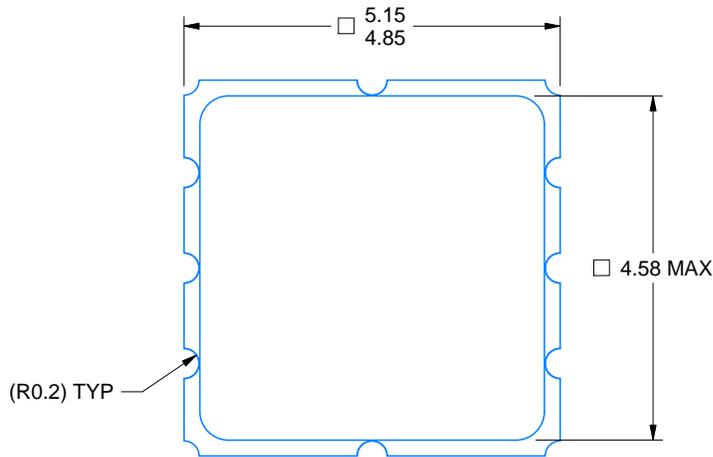
FKH0008A



PACKAGE OUTLINE

LCCC - 1.6 mm max height

LEADLESS CERAMIC CHIP CARRIER



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NOTES:

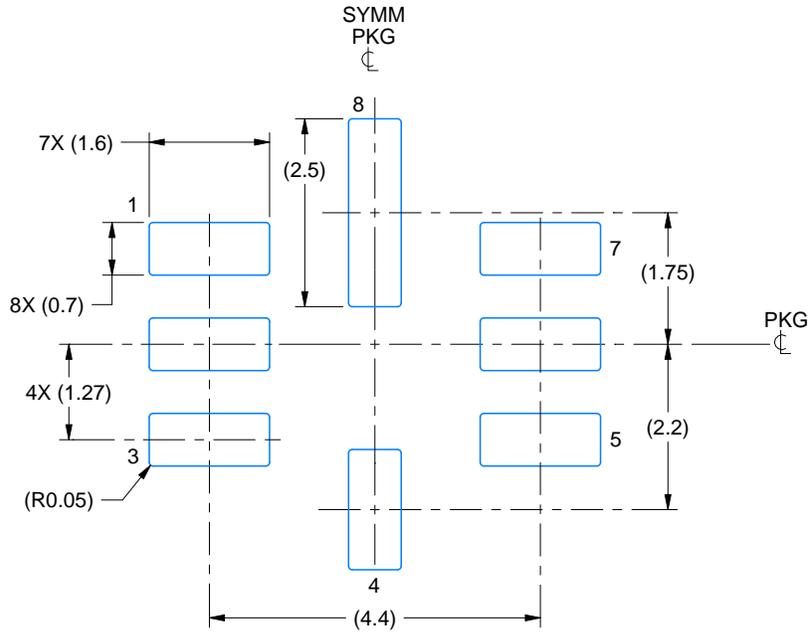
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M
- 2. This drawing is subject to change without notice.
- 3. Terminals are gold plated.

EXAMPLE BOARD LAYOUT

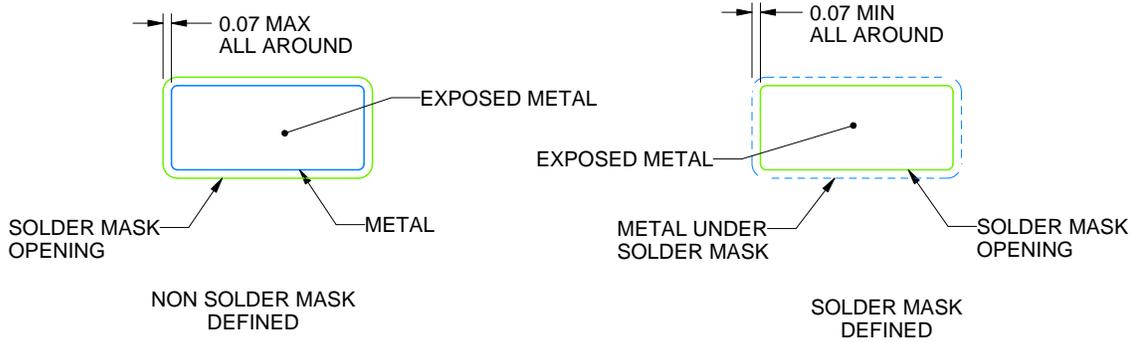
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LCCC - 1.6 mm max height

LEADLESS CERAMIC CHIP CARRIER



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:10X



SOLDER MASK DETAILS

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NOTES: (continued)

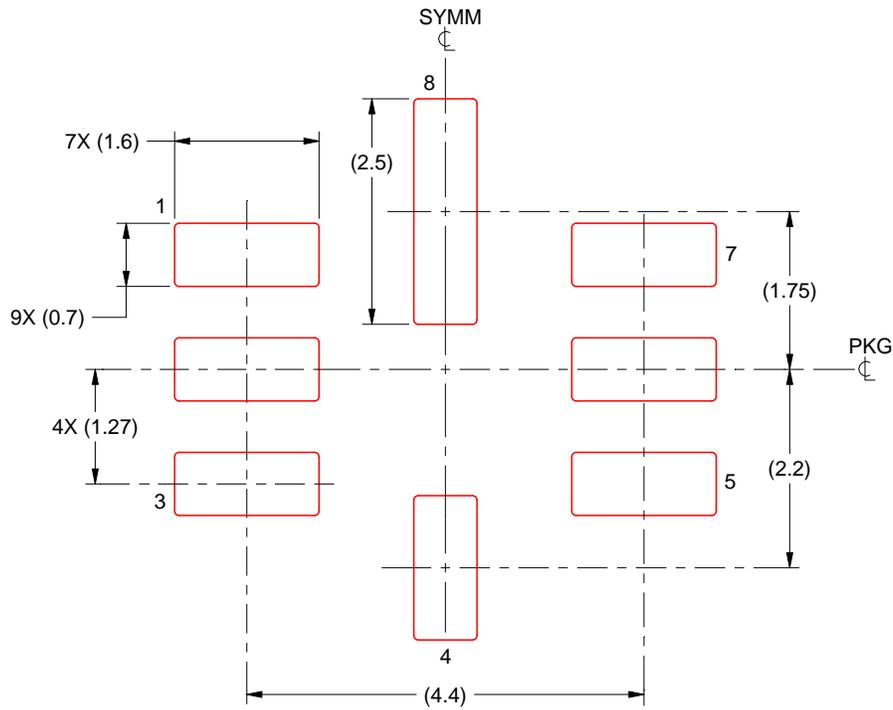
4. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

EXAMPLE STENCIL DESIGN

FKH0008A

LCCC - 1.6 mm max height

LEADLESS CERAMIC CHIP CARRIER



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:12X

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NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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